Item	Quantity	Part Reference	Value	Package	Description	Manufacturer	Manufacturer Part Number	Comments
1	10	C1 C6 C8 C9 C12 C14 C17 C20 C22 C31	100nF	0402	CAP, CERAMIC, 100nF, 16V, X7R, 10%, 0402	Murata	GRM155R71C104KA88D	
2	1	C2	1.0uF	0603	CAP, CERAMIC, 1.0uF, 10V, X7R, 10%, 0603	Kemet	C0603C105K8RACTU	
3	3	C3 C4 C28	1uF	0805	CAP, CERAMIC, 1uF, 50V, X7R, 10%, 0805	TDK Corporation	C2012X7R1H105K125AB	
4	2	C5 C24	10uF	1210	CAP, CERAMIC, 10uF, 50V, X7R, 10%, 1210	Murata	GRM32ER71H106KA12L	
5	1	C7	47nF	0402	CAP, CERAMIC, 47nF, 10V, X5R, 10%, 0402	Panasonic	ECJ0EB1A473K	
6	1	C11	1uF	0402	CAP, CERAMIC, 1uF, 6.3V, X7R, 10%, 0402	Kemet	C0402C105K9RACTU	
7	3	C13 C16 C37	4.7uF	0805	CAP, CERAMIC, 4.7uF, 10V, X7R, 10%, 0805	TDK Corporation	C2012X7R1A475K	
8	4	C15 C18 C21 C23	10nF	0201	CAP, CERAMIC, 10nF, 10V, X5R, 10%, 0201	Panasonic	ECJZEB1A103K	
9	4	C19 C30 C34 C35	10uF	0805	CAP, CERAMIC, 10uF, 10V, X7R, 10%, 0805	Murata	GRM21BR71A106KE51L	
10	4	C25 C26 C29 C33	100nF	0603	CAP, CERAMIC, 100nF, 50V, X7R, 10%, 0603	AVX	06035C104KAT2A	
11	1	C27	27nF	0603	CAP, CERAMIC, 27nF, 25V, X7R, 10%, 0603	AVX	06033C273KAT2A	
12	1	C32	1000pF	0603	CAP, CERAMIC, 1000pF, 50V, C0G (NPO), 5%, 0603	Panasonic	ECJ1VC1H102J	
13	1	C36	2.2uF	0603	CAP, CERAMIC, 2.2uF, 10V, X7R, 10%, 0603	Murata	GRM188R71A225KE15D	
14	1	D1	60V	POWERDI123	1.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER POWERDI123	DIODES INC	DFLS160-7	
15	1	J1	HDR-28-2X14-P(FTE)		CONN, HEADER, VERTICAL, 2x14, 28 PIN, .0315 PITCH, SMT	Samtec	FTE-114-01-G-DV	
16	1	J2	SMB-JACK-SMT-J		CONN, 50E SMB, Straight Jack, Receptacle , 3 Pin, Surface Mount	Emerson Network P	131-3711-201	
17	3	L1 L2 L4	4.7uH	2012	IND,POWER,WIRE-WOUND CHIP,SMD,4.7uF,700mA,+/-20%,2012	TAIYO YUDEN	BRC2012T4R7MD	

18	1	L3	100uH	2518	IND,POWER,WIRE-WOUND CHIP,SMD,100uF,300mA,+/-10%,2518	Taiyo Yuden	BRC2518T101K	
19	2	L5 L6	1.4A	0603	IND, FERRITE CHIP, 220 OHM AT 100MHz, 0.1 OHM DC, 0603	Murata	BLM18PG221SN1D	
20	1	L7	10uH	122X122X50	IND, POWER, SMD, .122"LX.122"WX.48"H	TDK Corporation	VLS3012T	
21	1	L8	2.2uH	0805	IND, CHIP COIL, MULTILAYER, SMD, 2.2uH, 0.8A, +/-25%, 0805	Murata	LQM21PN2R2NGC	
22	7	R1 R2 R5 R11 R12 R14 R17	10.0K	0402	RESISTOR, PRECISION THICK FILM CHIP, SMD, 10.0K, 0.1W, 1%, 0402	Panasonic	ERJ2RKF1002X	
23	1	R3	49.9	0603	RESISTOR, PRECISION THICK FILM CHIP, SMD, 49.9 OHM, 0.1W, 1%, 0603	Panasonic	ERJ3EKF49R9V	
24	1	R4	100K	0402	RESISTOR, THICK FILM CHIP, SMD, 100K, 0.063W, 5%, 0402	Panasonic	ERJ2GEJ104X	
25	1	R6	0	0603	RESISTOR, THICK FILM CHIP, SMD, 0 OHM JUMPER, 0.1W, 5%, 0603	Panasonic	ERJ3GEY0R00V	
26	2	R7 R8	4.7K	0402	RESISTOR, PRECISION THICK FILM CHIP, SMD, 4.7K, 0.1W, 1%, 0402	Panasonic	ERJ2RKF4701X	
27	1	R13	61.9K	0603	RESISTOR, PRECISION THICK FILM CHIP, SMD, 61.9K , 0.1W, 1%, 0603	Panasonic	ERJ3EKF6192V	
28	1	R15	8.06K	0603	RESISTOR, PRECISION THICK FILM CHIP, SMD, 8.06K, 0.1W, 1%, 0603	Panasonic	ERJ3EKF8061V	
29	1	R16	49.9K	0603	RESISTOR, THICK FILM CHIP, SMD, 49.9K, 0.1W, 1%, 0603	Yageo	RC0603FR-0749K9L	
30	1	TP1	TSTPT-5016		CONN, TERMINAL, TEST POINT COMPACT, .015 THICK, SMT	Keystone Electronics	5016	
31	1	U1	DS90UB913A-Q1	WQFN32	IC,25 to100 MHz 10/12-Bit FPD-Link III SERIALIZER AND DESERIALIZER	Texas Instruments	DS90UB913A-Q1	
32	1	U2	27MHz		OSC, CRYSTAL CLOCK, SMD, CMOS, 3.3V, 8mA, 27MHz, 3.2MM x 2.5MM x 0.85MM	Abracon Corp.	ASEMB-27.000MHZ-LC	

33	1	U3	LM34919	DSBGA12	IC, VOLTAGE REGULATOR,ULTRA-SMALL 50-V 600-mA CONSTANT ON-TIME BUCK SWITCHING REGULATOR	Texas Instruments	LM34919C	
34	1	U4	TPS62231	SON6	2 MHz / 3 MHz ULTRA SMALL STEP DOWN CONVERTOR IN 1x1.5 SON PACKAGE	TEXAS INSTRUMENT	TPS62231	

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